

Title (en)
KINIZ ALLOY HAVING HOMOGENEOUS MICROSTRUCTURE

Title (de)
KINIZLEGIERUNG MIT HOMOGENER MIKROSTRUKTUR

Title (fr)
ALLIAGE KINIZ AYANT UNE MICROSTRUCTURE HOMOGÈNE

Publication
EP 3985140 A4 20230726 (EN)

Application
EP 20823504 A 20200330

Priority
• KR 20190068807 A 20190611
• KR 2020004335 W 20200330

Abstract (en)
[origin: EP3985140A1] The present disclosure relates to KINIZ alloys having a homogeneous microstructure. A KINIZ alloy includes: copper (Cu) and iron (Fe) in a total amount of 75 wt% to 95 wt%; and nickel (Ni) in an amount of 1 wt% to 20 wt%, zirconium (Zr) in an amount of 0.1 wt% to 5.0 wt%, and a balance of inevitable impurities. A KINIZ alloy includes: copper (Cu) and iron (Fe) in a total amount of 75 wt% to 95 wt%; and manganese (Mn) in an amount of 2.0 wt% to 5.0 wt%, zirconium (Zr) in an amount of 0.3 wt% to 1.0 wt%, and a balance (excluding 0 %) of inevitable impurities.

IPC 8 full level
C22C 9/00 (2006.01); **C22C 30/02** (2006.01); **C22C 38/04** (2006.01); **C22C 38/08** (2006.01); **C22C 38/14** (2006.01); **C22C 38/16** (2006.01); **C22F 1/08** (2006.01)

CPC (source: CN EP KR US)
B22D 27/04 (2013.01 - CN); **B22D 46/00** (2013.01 - CN); **C22C 1/1036** (2013.01 - CN); **C22C 1/1052** (2023.01 - CN); **C22C 9/00** (2013.01 - CN EP US); **C22C 30/02** (2013.01 - EP); **C22C 33/04** (2013.01 - CN); **C22C 38/04** (2013.01 - CN EP US); **C22C 38/08** (2013.01 - CN EP KR US); **C22C 38/14** (2013.01 - CN EP KR US); **C22C 38/16** (2013.01 - CN EP KR US); **C22F 1/08** (2013.01 - EP)

Citation (search report)
• [XAI] JP 2000256766 A 20000919 - SANYO SPECIAL STEEL CO LTD
• [XAI] JP H0578766 A 19930330 - TOSHIBA CORP
• See references of WO 2020251145A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 3985140 A1 20220420; **EP 3985140 A4 20230726**; CN 113454259 A 20210928; JP 2022521606 A 20220411; KR 102274566 B1 20210707; KR 20200141811 A 20201221; US 2022145434 A1 20220512; WO 2020251145 A1 20201217

DOCDB simple family (application)
EP 20823504 A 20200330; CN 202080015273 A 20200330; JP 2021549635 A 20200330; KR 20190068807 A 20190611; KR 2020004335 W 20200330; US 202017434398 A 20200330